



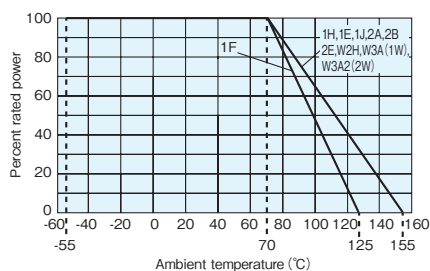
① Protective coating	④ Ni plating
② Resistive film	⑤ Solder plating
③ Inner electrode	⑥ Ceramic substrate

Type (Inch Size Code)	Dimensions (mm)					Weight (g) (1000pcs)
	L	W	c	d	t	
1F (01005)	0.4±0.02	0.2±0.02	0.10±0.03	0.11±0.03	0.13±0.02	0.04
1H (0201)	0.6±0.03	0.3±0.03	0.1±0.05	0.15±0.05	0.23±0.03	0.14
1E (0402)	1.0 ^{+0.1} _{-0.05}	0.5±0.05	0.2±0.1	0.25 ^{+0.05} _{-0.1}	0.35±0.05	0.68
1J (0603)	1.6±0.2	0.8±0.1	0.3±0.1	0.3±0.1	0.45±0.1	2.14
1J AT (0603)			0.35±0.15	0.5±0.2		
2A (0805)	2.0±0.2	1.25±0.1	0.4±0.2	0.3 ^{+0.2} _{-0.1}	0.5±0.1	4.54
2A AT (0805)			0.45±0.25	0.6±0.2	0.55±0.1	
2B (1206)	3.2±0.2	1.6±0.2	0.5±0.3	0.4 ^{+0.2} _{-0.1}	0.6±0.1	9.14
2B AT (1206)			0.55±0.35	0.8±0.2		
2E (1210)		2.6±0.2	0.4 ^{+0.2} _{-0.1}	0.65±0.15		
W2H (2010) ^{※1}	5.0±0.2	2.5±0.2	0.5±0.3		24.3	
W3A (2512) ^{※1}	6.3±0.2	3.1±0.2				0.65±0.15
W3A2 (2512) ^{※1}						

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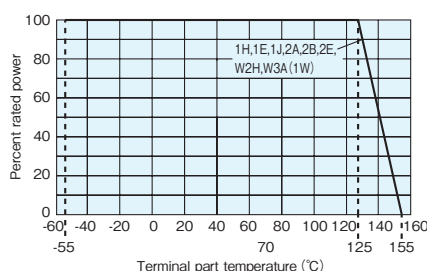
Derating Curve

Ambient temperature



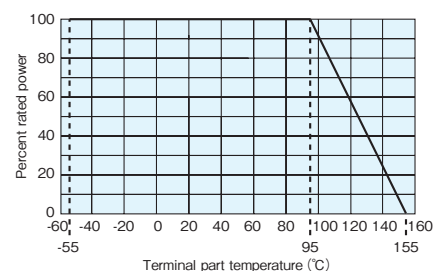
For resistors operated at an ambient temperature of 70°C or higher, the power shall be derated in accordance with the above derating curve.

Terminal part temperature



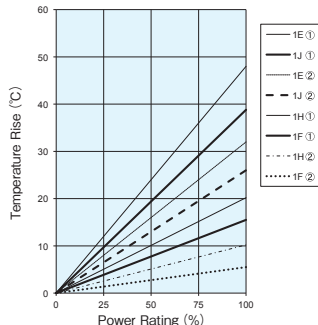
When the terminal part temperature of the resistor exceeds the rated terminal part temperature shown above, the power shall be derated according to the derating curve.

※Please refer to "Introduction of the derating curves based on the terminal part temperature" on the beginning of our catalog before use.

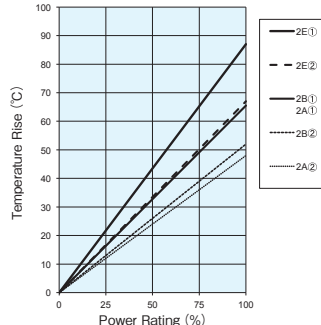
Terminal part temperature
RK73H W3A2


Temperature Rise

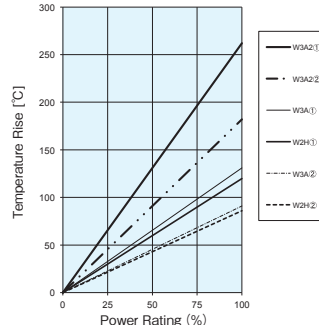
RK73H 1F-1J



RK73H 2A-2E

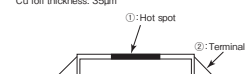


RK73H W2H-W3A2



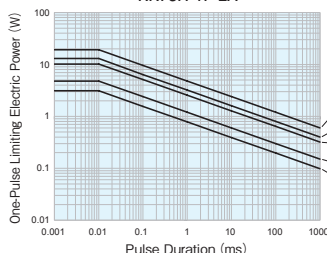
Regarding the temperature rise, the value of the temperature varies per conditions and board for use since the temperature is measured under our measuring conditions.

Measurement condition
Room temperature: 25°C
PCB: FR-4t = 1.6mm
Cu foil thickness: 35μm

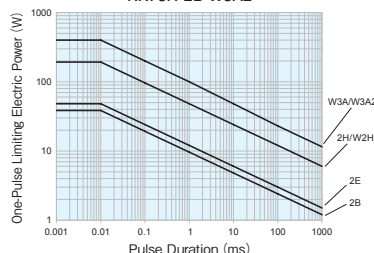


One-Pulse Limiting Electric Power

RK73H 1F-2A



RK73H 2B-W3A2



The maximum applicable voltage is equal to the max. overload voltage. Please ask us about the resistance characteristic of continuous applied pulse. The pulse endurance values are not assured values, so be sure to check the products on actual equipment when you use them.

Performance

Test Items	Performance Requirements $\Delta R \pm$ (%+0.1%)		Test Methods
	Limit	Typical	
Resistance	Within specified tolerance	—	25°C
T.C.R.	Within specified T.C.R.	—	+25°C / -55°C and +25°C / +125°C
Overload (Short time)	2	1 : 1F 0.5 : others	Rated voltage $\times 2.5$ for 5s (1E, 2B, W3A2 : Rated voltage $\times 2$ for 5s)
Resistance to soldering heat	1 : 1F~W3A ($10\Omega \leq R \leq 1M\Omega$) 3 : 1H~W3A ($R < 10\Omega$, $R > 1M\Omega$)	0.5 : 1F~W3A ($10\Omega \leq R \leq 1M\Omega$) 1 : 1H~W3A ($R < 10\Omega$, $R > 1M\Omega$)	260°C $\pm 5^\circ\text{C}$, 10s ± 1 s
Rapid change of temperature	1 : 1F, Characteristic [A] (Heat shock resistance) 0.5 : others	0.5 : 1F, Characteristic [A] (Heat shock resistance) 0.3 : others	Characteristic [Ni] (Standard) : -55°C (30min.) / +125°C (30min.) 100 cycles Characteristic [A] (Heat shock resistance) : -55°C (30min.) / +125°C (30min.) 1000 cycles
Moisture resistance	2 : 1J, 2A, 2B 3 : others	0.75 : 1J, 2A, 2B 1.5 : 1F 1 : others	40°C $\pm 2^\circ\text{C}$, 90%~95%RH, 1000h 1.5h ON / 0.5h OFF cycle
Endurance at 70°C or rated terminal part temperature	2 : 1J, 2A, 2B 3 : others	0.75 : 1J, 2A, 2B 1 : others	70°C $\pm 2^\circ\text{C}$ or rated terminal part temperature $\pm 2^\circ\text{C}$ 1000h 1.5h ON / 0.5h OFF cycle
High temperature exposure	1	0.5 : 1F 0.3 : others	+125°C, 1000h : 1F +155°C, 1000h : 1H, 1E, 1J, 2A, 2B, 2E, W2H, W3A, W3A2

Precautions for Use

- The substrate of chip resistors is alumina. Cracks may occur at the connection of solder (solder fillet portion) due to the difference of the coefficient of thermal expansion from a mounting board when heat stress like heat cycle, etc. are repeatedly given to them. Care should be taken to the occurrence of the cracks when the change in ambient temperature or ON/OFF of load is repeated, especially when large types of W2H/W3A/W3A2 which have large thermal expansion and also self heating. By general temperature cycle test using glass-epoxy (FR-4) boards under the maximum/minimum temperatures of operating temperature range, the crack does not occur easily in the types of 1F~2E, but the crack tends to occur in the types of W2H/W3A/W3A2. The occurrence of the crack by heat stress may be influenced by the size of a pad, solder volume, heat radiation of mounting board etc., so please pay careful attention to designing when a big change in ambient temperature and conditions for use like ON/OFF of load can be assumed.
- Care should be taken that RK73H1F may be damaged when static electricity occurs and is applied in the equipment.